

- c) other additives selected from the group consisting of selected from the group consisting of HCl, aliphatic alcohols, butylated hydroxytoluene, Agidol-2,2,6-di-tert-butyl-4[(dimethylamino)methyl]phenol, 2,6-di-tert-4N,N-dimethylaminomethylphenol, borax, ethylene glycol, ZnSO₄, methanol, propanol, poly(oxyethylene)lauryl ether, malic acid, HOOC(CX₂)_nCOOH wherein X=OH, amine, H and n=1-4), 3% tartaric acid, 1% ethylene glycol, 1,2,4-triazole, 1,2,3-triazole, tetrazole, nonionic surfactant, ethanol, trifluoroethanol, SiF₆, organic salt surfactant, polyvinyl alcohol, diphenylsulfamic acid, sodium oxalate, bezotriazole, sodium lignosulfonate, glycol, gelatin carboxymethylcellulose, amines, heavy metal salts, salts of Cu and Ta, KCl, CuCl₂, SnCl₂, propylene glycol, 2-ethyl-hexylamine, copper carbonate, low molecular weight alcohols, glycols, phenols, aliphatic alcohols, polyvinylalcohols, anionic surfactants, cationic surfactants, fluorocarbon-based surfactants, nonionic surfactants having the properties of preferentially adhering to certain materials, modifying thereby the chemical reactivity where so adhered, polyvinyl alcohol solution stabilizers and species inhibiting spontaneous decomposition of oxidizing agents, wetting agents and mixtures thereof].
12. (Amended) [An etching solution for chemical mechanical planarization of a Cu/Ta/TaN surface as in] The etching solution of claim 1 further comprising abrasive particles selected from the group consisting SiO₂, Al₂O₃ metallic and solid elemental particles, polymer particles, oxides, carbides, fluorides, carbonates, borides, nitrides, hydroxides of Al, Ag, Au, Ca, Ce, Cr, Cu, Fe, Gd, Ge, La, In, Hf, Mn, Ng, Ni, Nd, Pb, Pt, P, Sb, Sc, Sn, Tb, Ti, Ta, Th, Y, W, Zn, Zr, and mixtures thereof.
19. (Added) A method of accomplishing chemical mechanical planarization of a Cu/Ta/TaN surface comprising:
providing an etching solution including a combination selected from the group consisting of (i) H₂O₂ with H₃PO₄, H₂SO₄, HNO₃, oxalic acid, acetic acid, or organic acid, (ii) HNO₃ with H₃PO₄, or H₂SO₄; and (iii) an oxidizing reagent with HF;

applying the solution to the surface; and
planarizing both the Cu and at least one of the Ta and TaN during a single processing
step.

20. (Added) The method of claim 19, wherein the etching solution is selected from the group consisting of H_2O_2 with H_3PO_4 , H_2SO_4 , HNO_3 , oxalic acid, or organic acid.
21. (Added) The method of claim 19, wherein the etching solution is selected from the group consisting of HNO_3 with H_3PO_4 , or H_2SO_4 .
22. (Added) The method of claim 19, wherein the etching solution is selected from the group consisting of an oxidizing reagent with HF.
23. (Added) The method of claim 19, further including in the etching solution an additive selected from the group consisting of selected from the group consisting of HCl, aliphatic alcohols, butylated hydroxytoluene, Agidol-2,2,6-di-tert-butyl-4[(dimethylamino)methyl]phenol, 2,6-di-tert-4N,N-dimethylaminomethylphenol, borax, ethylene glycol, ZnSO_4 , methanol, propanol, poly(oxyethylene)lauryl ether, malic acid, $\text{HOOC}(\text{CX}_2)_n\text{COOH}$ wherein $\text{X}=\text{OH}$, amine, H and $n=1-4$), 3% tartaric acid, 1% ethylene glycol, 1,2,4-triazole, 1,2,3-triazole, tetrazole, nonionic surfactant, ethanol, trifluoroethanol, SiF_6 , organic salt surfactant, polyvinyl alcohol, diphenylsulfamic acid, sodium oxalate, bezotriazole, sodium lignosulfonate, glycol, gelatin carboxymethylcellulose, amines, heavy metal salts, salts of Cu and Ta, KCl, CuCl_2 , SnCl_2 , propylene glycol, 2-ethyl-hexylamine, copper carbonate, low molecular weight alcohols, glycols, phenols, aliphatic alcohols, polyvinylalcohols, anionic surfactants, cationic surfactants, fluorocarbon-based surfactants, nonionic surfactants having the properties of preferentially adhering to certain materials, modifying thereby the chemical reactivity where so adhered, polyvinyl alcohol solution stabilizers and species inhibiting spontaneous decomposition of oxidizing agents, wetting agents and mixtures thereof.

24. (Added) The method of claim 19, further including in the etching solution at least one of CuCl, FeCl, and FeCl₃, in the etching solution.
25. (Added) The method of claim 19, further including in the etching solution at least one of Cu(NO₃)₂, CuSO₄, EDTA, FeNO₃, KOH, K₂S₂O₅, (NH₄)₂S₂O₈, CuNH₄Cl₃, NaOH, NaClO₃, NaNO₃, Na₂S₂O₈, NH₄F, and NH₄OH and in the etching solution.
26. (Added) The method of claim 19, further including in the etching solution at least one of a molybdenum salt and phenolsulfonic acid in the etching solution.
27. (Added) The method of claim 19, further comprising including abrasive particles selected from the group consisting SiO₂, Al₂O₃ metallic and solid elemental particles, polymer particles, oxides, carbides, fluorides, carbonates, borides, nitrides, hydroxides of Al, Ag, Au, Ca, Ce, Cr, Cu, Fe, Gd, Ge, La, In, Hf, Mn, Ng, Ni, Nd, Pb, Pt, P, Sb, Sc, Sn, Tb, Ti, Ta, Th, Y, W, Zn, Zr, and mixtures thereof.
28. (Added) The method of claim 19, wherein the step of planarizing removes the Cu and at least one of the Ta and TaN with approximately 1:1 selectivity.
29. (Added) The etching solution of claim 1 comprising H₂O₂.
30. (Added) The etching solution of claim 1 comprising H₃PO₄.
31. (Added) The etching solution of claim 1 comprising H₂SO₄.
32. (Added) The etching solution of claim 1 comprising HNO₃.
33. (Added) The etching solution of claim 1 comprising an organic acid.